**NOTES**

1. **MATERIALS:**
   - LEAD FRAME: COPPER 194FH, THK = 0.008
   - BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QPTECHNOLOGIES FOR DETAILS.

2. **FINISH:**
   - LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 200 TO 300 MICROINCHES (5.0um-7.6um) THICK.
   - GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICROINCHES (1um-2um) THICK).
   - BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)

3. **PACKAGE MISMATCH:** BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.

4. **UNLESS OTHERWISE SPECIFIED,** RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.253mm MAX.

5. **PACKAGE CONFORMS TO JEDEC MO-220**

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**Dimensions: (in millimeters)**

- PIN #1 ID: 0.40 x 45° CHAMFER
- CENTER PAD: 0.350 ALL AROUND
- CAVITY: 0.253
- PIN #1 ID: 0.253
- SECTION A-A: 12.0° ALL AROUND
- CENTER PAD: 0.250 WIDTH
- PIN #1 ID: 0.203
- TOP VIEW: 3.000
- CENTER PAD: 0.400 ALL AROUND
- ALL AROUND: 0.150
- ALL AROUND: 0.203
- ALL AROUND: 0.714
- ALL AROUND: 0.494
- ALL AROUND: 0.400
- ALL AROUND: 0.800
- TOP VIEW: 4.500
- TOP VIEW: 4.000
- TOP VIEW: 0.597
- TOP VIEW: 0.253
- TOP VIEW: 0.203
- TOP VIEW: 6.940
- TOP VIEW: 7.240